

Copper-paste for circuit-forming
【KG-2438】

Improvements in Sintering Temperature, Adhesion Strength, Firing Atmosphere, and Stability – Copper Paste for Circuit Formation

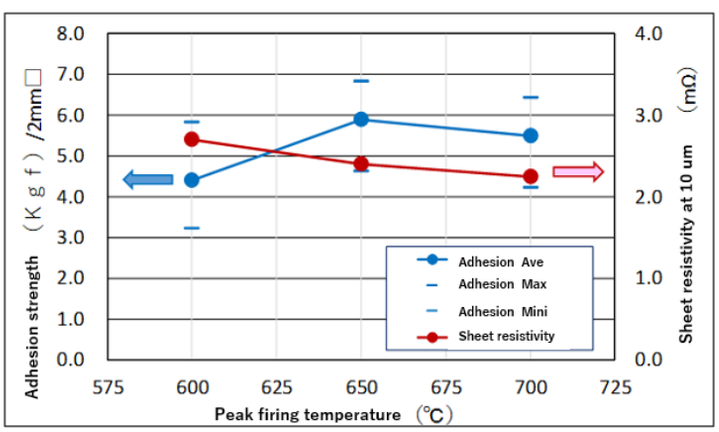
Advantage

- ☑ Copper Paste Features: Low resistivity comparable to silver paste
- ☑ Achieves low sintering temperature
- ☑ High adhesion strength enhances circuit reliability
- ☑ Excellent storage stability enables long-term preservation

Characteristics

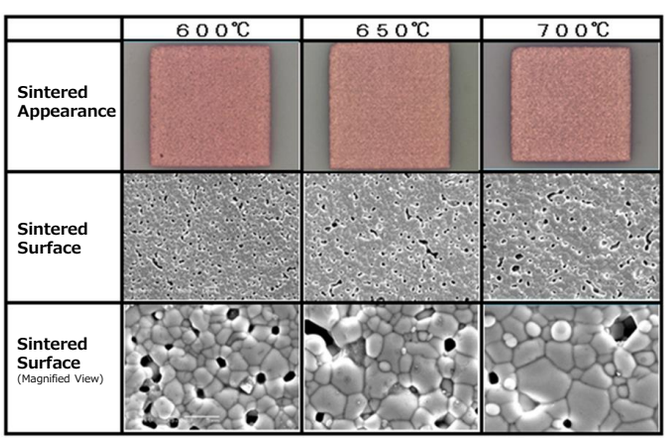
Adhesion Strength × Sintering Temperature

Adhesion strength and resistance to firing temperature



State of Sintered Film

Fired film condition at different firing temperatures



Adhesive strength: It was measured peel strength by soldering a wire of 0.6mmϕ to 2mm×2mm pads of KG-2438 fired at a predetermined peak temperature on an alumina substrate with soldering.

Recommended Process Conditions

Viscosity	250~350Pa·s(10rpm)
Sheet resistivity	≦5.0mΩ (Sheet resistivity at 10 um)
Adhesion strength	≧3kgf(30N)/2mm□

Adhesion strength and resistance

Drying	120℃ max. in air, 5 minutes to 30 minutes
Solder	Peak in nitrogen 600℃ or more for 9 minutes or more (oxygen concentration ≦50ppm)
Fireing	Sn-3.0Ag-0.5Cu

If you have any question about this product, please feel free to contact us.
https://crossmining.smm-g.com/

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